Tool ID: 501
Tool Location: 118

Equipment Information Sheet

E-Beam Lithography Spinners

Manager: Giovanni Sartorello 607-254-4853
Backup: John Treichler 607-254-4949

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Face shields must be worn at ALL TIMES.
- Close spinner lid before spinning. The lid will contain fragments if vacuum fails or the substrate breaks.
- No solvents or materials containing solvents outside hoods, except substrates for immediate baking, and bottles for immediate storage.
- Dispose of pipettes, wipers, swabs etc. in appropriate receptacles. All waste with solvent or resist must be in a vented container.

USAGE RESTRICTIONS

Please review electron beam lithography training materials, in AFS, at: shares - public - processes_from_cnf_staff - ElectronBeamLithography - TrainingMaterials (accessible on any general use PC or CNF Thin station at CNF)

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 0 minutes

- No scheduling for these tools

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Use only approved ebeam lithography resists and solvents

Last Updated: 05/30/2025